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APPLICATION NO. FILIN		ILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.		
10/726,399		12/03/2003	David Forehand	MEM 2657001	5565		
21909	7590	10/17/2005		EXAM	EXAMINER		
CARR L	.LP NDERS SQU	IARF	MITCHELL, JAMES M				
	KSON STRE		ART UNIT	PAPER NUMBER			
DALLAS	s, TX 7520	2	2813				
			DATE MAIL ED: 10/17/2005				

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.		Applicant(s)							
O.C. A. (*	10/726,39	9	FOREHAND, DAV	ID	(fm)					
Office Action S	Examiner		Art Unit							
		James M.	Mitchell	2813						
The MAILING DATE Period for Reply	of this communication ap	pears on the	cover sheet with the c	orrespondence add	dress					
A SHORTENED STATUTO WHICHEVER IS LONGER, - Extensions of time may be available after SIX (6) MONTHS from the mai - If NO period for reply is specified ab - Failure to reply within the set or exte Any reply received by the Office late earned patent term adjustment. See	FROM THE MAILING D under the provisions of 37 CFR 1. ling date of this communication. ove, the maximum statutory period ended period for reply will, by statut or than three months after the mailing	DATE OF TH 136(a). In no eve will apply and wi e, cause the appl	IIS COMMUNICATION int, however, may a reply be timed to the spire SIX (6) MONTHS from the ication to become ABANDONE	I. lely filed the mailing date of this co O (35 U.S.C. § 133).						
Status										
2a) ☐ This action is FINAL.3) ☐ Since this application	unication(s) filed on <u>15 J</u> 2b)⊠ Thi is in condition for allowa with the practice under	s action is nance except	for formal matters, pro		merits is	s				
Disposition of Claims										
5) Claim(s) is/are 6) Claim(s) 1-12,24-33,4 7) Claim(s) is/are 8) Claim(s) are s Application Papers 9) The specification is obtained and the second s	n(s) 13-23,34-43,54-63,6 e allowed. 14-53,64 and 66 is/are re- e objected to. subject to restriction and/or objected to by the Examina on 03 December 2003 is/a est that any objection to the heet(s) including the correct	ejected. or election re er. are: a)⊠ ac drawing(s) betion is require	equirement. ccepted or b) objected in abeyance. See bed if the drawing(s) is object	ed to by the Exam 37 CFR 1.85(a). ected to. See 37 CF	R 1.121(d).				
Priority under 35 U.S.C. § 119)									
 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some * c) None of: 1. Certified copies of the priority documents have been received. 2. Certified copies of the priority documents have been received in Application No 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received. 										
Attachment(s) 1) Notice of References Cited (PTC2) Notice of Draftsperson's Patent (PTC3) Information Disclosure Statemer Paper No(s)/Mail Date	Drawing Review (PTO-948))	4) Interview Summary Paper No(s)/Mail Da 5) Notice of Informal P 6) Other:	ite	-152)					

DETAILED ACTION

1. This office action is in response to applicant's election filed July 15, 2005

Election

- 2. Claims 13-23, 34-43, 54-63, 65 and 67 withdrawn from further consideration pursuant to 37 CFR 1.142(b), as being drawn to a nonelected invention, there being no allowable generic or linking claim. Applicant timely traversed the restriction (election) requirement in the reply filed on July 15, 2005.
- 3. Applicant's election with traverse of Group I in the reply filed on July 15, 2005 is acknowledged. The traversal is on the ground(s) that Group I and Group II involve the same process. This is not found persuasive.

Because per MPEP 806.05(e) another materially different apparatus can produce the process, such as having multiple apparatuses for performing each step (i.e. performing packaging in another facility), applicant's arguments are deemed unpersuasive. Likewise, contrary to applicant's assertion that the means is limited to the claimed process, since applicant's specification does not limit to a particular means (i.e. Pg. 8,Lines 15-20), the means for deposing can be different than what is claimed. For the reasons stated, *supra*, the restriction requirement is still deemed proper and is therefore made FINAL.

Application/Control Number: 10/726,399 Page 3

Art Unit: 2813

A person shall be entitled to a patent unless -

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

- 5. Claim 1-5, 8, 11, 25-28, 45-48, 51, 52, 64 and 66 are rejected under 35 U.S.C. 102(e) as being anticipated by Carley (U.S. 2004/0166603).
- 6. Carley (Fig. 5B, 7C, 8D) discloses:

(cl. 1, 45) a method for packaging at least one microscopic device, comprising: applying a sacrificial material (12, 16) to at least one microscopic device (14); applying a layer of structural material (18) adjacent the sacrificial material, the layer of structural material forming a housing adjacent at least a portion of the sacrificial material; creating one or more apertures (20) in the housing of structural material to expose at least a portion of the adjacent sacrificial material; removing the sacrificial layer (Par. 0037), wherein the housing of structural material with at least one aperture remains (Fig. 7C); depositing a protective material (26a-c) adjacent the housing of structural material overlaying at least one aperture of the housing; and curing the protective material (Par. 0049); (cl. 2, 64) providing a gas atmosphere, wherein the pressure is greater than or equal to 1 Pascal (Pa) (Par. 0050) providing a temperature of less than 600 degrees Celsius (C) (Par. 0049);

(cl. 3, 4, 46, 47) wherein etch rate ¹ is higher than structural material composed of a photoresist or polyimide (Par. 0036);

¹ Same structural and sacrificial material as claimed.

Art Unit: 2813

(cl. 5, 48) wherein the structural layer is selected from a group of Silicon Dioxide (SiO2) and Silicon Nitride (Si3N4) (Par. 0036);

- (cl. 8, cont. cl. 25, 45, 51) and removing the sacrificial layer comprises use of either plasma ashing or plasma etching (Par. 0036);
- (cl. 11, 52) the structural layer having a thickness between .2 and about 10 microns (Par. 0052);
- (cl. 66) and protective material extends² at least into one aperture ("seals port [holes]";Par. 0012) and allowing layer to harden (i.e. layer rigid; Par. 0013-0014)

Claim Rejections - 35 USC § 103

- 7. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 8. Claims 12 and 53 are rejected under 35 U.S.C. 103(a) as being unpatentable over Carley et al. (U.S. 2004/0166603).
- 9. Carley discloses the elements of paragraph 6 of this office action and a thickness for its sacrificial layer (i.e. 3 dimensional) and claimed structure, but does not disclose the thickness between .2 and 10 microns.

² Note even a layer that extends horizontally over a hole/aperture would extend into the hole region (i.e. open space/area), although not extending vertically into the hole.

- 10. In any case, applicant has not disclosed that the claimed thickness is for a particular unobvious purpose, produce an unexpected result, or are otherwise critical. Hence the limitation would have been obvious, since it has been held that mere dimensional limitations are prima facie obvious absent a disclosure that the limitations are for a particular unobvious purpose, produce an unexpected result, or are otherwise critical. See, for example, In re Rose, 220 F.2d 459, 105 USPQ 237 (CCPA 1955); In re Rinehart, 531 F.2d 1048, 189 USPQ 143 (CCPA 1976); Gardner v. TEC Systems, Inc., 725 F.2d 1338, 220 USPQ 777 (Fed. Cir. 1984), cert. denied, 469 U.S. 830, 225 USPQ 232 (1984); In re Dailey, 357 F.2d 669, 149 USPQ 47 (CCPA 1966).
- 11. Claims 6, 7, 49, 50 are rejected under 35 U.S.C. 103(a) as being unpatentable over Carley et al. (U.S. 2004/0166603) as applied to claim 2 and 25 and further in combination with Yang et al. (U.S. 2004/0046835).
- 12. Carley does not appear to disclose the step of removing by sputter etching or ion beam milling or chemical etching.
- 13. However Carley discloses the same invention except that removal is through plasma etch instead of through sputter, ion beam milling or chemical etching. Yang shows that plasma, sputter etching or ion beam milling or chemical etching is equivalent processes that form equivalent structures known in the art known. Therefore, because these processes are art recognized equivalents at the time the invention was made, one of ordinary skill in the art would have found it obvious to substitute the use of for example a chemical etch instead of a plasma etch to remove material.

Application/Control Number: 10/726,399 Page 6

Art Unit: 2813

14. Claims 9, 10, 24-28, 31-33 and 44 are rejected under 35 U.S.C. 103(a) as being unpatentable over Carley et al. (U.S. 2004/0166603) in combination with Farnworth et al. (U.S. 2002/0123171).

- 15. Carley discloses the elements stated in paragraph 6 of this office action and further discloses the step of depositing the protective material (Par. 0042) into holes (Par. 0012) and at least a portion of the surface of the housing (Par. 0043) with no material in a moveable region (22), but does not appear to explicitly disclose depositing protective material by allowing the protective material to flow into at least a portion of an aperture.
- 16. Farnworth teaches deposition by flowing³ a material (Par. 0032).
- 17. It would have been obvious to one of ordinary skill in the art to incorporate a process of flowing material in order to provide to provide a protective layer on a surface as taught by Farnworh (Par. 0032) and as suggested by Carley (apply overlayer by "other known deposition processes"; Par. 0042).
- 18. With respect to the thickness limitation of claim 33, see paragraph 10 of this office action.
- 19. Claims 29 and 30 are rejected under 35 U.S.C. 103(a) as being unpatentable over Carley et al. (U.S. 2004/0166603) and Farnworth et al. (U.S. 2002/0123171) as applied to claim 25 and further in combination with Yang et al. (U.S. 2004/0046835).

³ Also wicking (i.e. capillary action in flowing of material)

Application/Control Number: 10/726,399

Art Unit: 2813

20. Carley does not appear to disclose the step of removing by sputter etching or ion beam milling or chemical etching.

Page 7

- 21. However see paragraph 13 of this office action.
- 22. Claims 1, 25 and 45 are rejected under 35 U.S.C. 103(a) as being unpatentable over Peterson et al. (U.S. 6,379,988) in combination with Peterson',084 (U.S. 6,661,084).
- 23. Peterson (Fig. 6E-H) discloses:
- (cl. 1, 25, 45) a method for packaging at least one microscopic device, comprising: applying a sacrificial material (15) to at least one microscopic device (10); applying a layer of structural material (14) adjacent the sacrificial material, the layer of structural material forming a housing adjacent at least a portion of the sacrificial material; creating one or more apertures (13) in the housing of structural material to expose at least a portion of the adjacent sacrificial material; removing the sacrificial layer (16), wherein the housing of structural material with at least one aperture remains (Fig. 6H); depositing a protective material/window (36) adjacent the housing of structural material overlaying at least one aperture of the housing.
- 24. Peterson does not appear to disclose curing the protective material,
- 25. Peterson'084 teaches curing a protective material (Col. 14, Lines 57-63).
- 26. It would have been obvious to one of ordinary skill in the art to incorporate a process of curing the protective layer in order to form a window as required by Peterson (item 36).

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Art Unit: 2813

Conclusion

27. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. The prior art discloses most notably in Bickford (U.S. 5,480,841) use of capillary action/wicking to fill holes.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to James M. Mitchell whose telephone number is (571) 272-1931. The examiner can normally be reached on M-F 8:00-4:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Carl Whitehead Jr. can be reached on (571) 272-1702. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Jmm // J // September 22, 2005

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